

09/403,543

ABSTRACT

A memory IC 10a includes a substrate (substrate on the transfer destination side) 21, and a memory cell array 71, a memory cell array 72, and a memory cell array 73 deposited on the substrate 21. The memory cell arrays 71, 72, and 73 are deposited, in that order, from the lower side in Fig. 21 by a method for transferring a thin film configuration. The method for the transfer includes the steps of forming a thin film device layer (memory cell array) on a support substrate with a separable layer therebetween, and irradiating the separable layer with light to cause a separation in the separable layer and /or at an interface so that the thin film device layer on the support substrate is transferred to the substrate 21.

MP 91
10
Engenierie
Gesellschaft m.b.H.
D-8048 Munich 80